

PACKAGE MATERIAL DECLARATION DATASHEET (PMDD)

Cypress Package Code	VZ	Body Size (mil/mm)	300 mils
Package Weight – Site 1	776 mg	Package Weight – Site 2	N/A

SUMMARY

The SOJ 24L Pb-Free package is compliant to RoHS. Cypress Ordering Part Numbers containing an “X” (e.g. CY7C1328G-133AXI, CY2308SXC-1HT) meet the Directive 2002/95/EC (RoHS) requirement.

ASSEMBLY Site 1 – Package Qualification Report # 091906 (See Note 1)

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report (Note 2)
Cadmium and Cadmium Compounds	0	< 5.0	CoA-VZ24-X
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Napthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.

Note 2: Report available from Cypress Sales Offices or Distributors.

Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered “non-existent in the product” or a natural impurity. In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor PMDD's are calculated using MSDS, Material Analysis Reports and Cypress Assembly site information.

Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B. MATERIAL COMPOSITION (Note 3)

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous material	PPM	% weight of substance per package
Lead frame	Base Material	Cu	7440-50-8	148.90	97.05%	191,849	19.18%
		Fe	7439-89-6	3.99	2.60%	5,142	0.51%
		Zn	7440-66-6	0.31	0.20%	396	0.04%
		P	7723-14-0	0.23	0.15%	297	0.03%
Lead Finish	External Plating	Sn	7440-31-5	254.3	100.00%	327,663	32.77%
Die Attach	Adhesive	Epoxy Resin	Proprietary	0.05	16.00%	62	0.01%
		Silver	7440-22-4	0.25	82.00%	317	0.03%
		Aromatic Amine	Proprietary	0.01	2.00%	8	0.00%
Die	Circuit	Si	7440-21-3	0.23	100.00%	296	0.03%
Wire	Interconnect	Au	7440-57-5	0.35	100.00%	451	0.05%
Mold Compound	Encapsulation	Solid Epoxy Resin	Proprietary	36.75	10.00%	47,352	4.74%
		Phenol Resin	Proprietary	36.75	10.00%	47,352	4.74%
		Fused Silica	60676-86-0	266.80	72.60%	343,771	34.38%
		Crystalline Silica	14808-60-7	18.38	5.00%	23,679	2.37%
		Carbon black	1333-86-4	3.68	1.00%	4,736	0.47%
		Antimony Trioxide	1309-64-4	5.15	1.40%	6,630	0.66%
Package Weight (mg):				776	% Total:		100%

II. DECLARATION OF PACKAGING / INDIRECT MATERIALS

Type	Material	Lead PPM	Cadmium PPM	Cr VI PPM	Mercury PPM	PBB PPM	PBDE PPM	Analysis Report (Note2)
Tape & Reel	Cover tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-COVT-R
	Carrier tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-CART-R
	Plastic Reel	< 5.0	< 5.0	< 5.0	< 10.0	< 50.0	< 45.0	CoA-PLRL-R
Tray	Tray	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Tube	Plastic Tube	< 5.0	< 5.0	< 5.0	< 5.0	< 1.0	< 1.0	CoA-PLTB-R
	End Plug	< 5.0	< 5.0	< 5.0	< 5.0	< 1.0	< 1.0	CoA-EPLG-R
	End Pin	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Others	Shielding bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-SBAG -R
	Moisture Barrier bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-MBBG-R
	Protective Band	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-PROB-R
	Shipping and Inner Box	< 10.0	< 4.0	< 4.0	< 5.0	-----	-----	CoA-ABOX-R
	Dessicant	< 10.0	< 2.0	< 2.0	< 1.0	< 3.0	< 3.0	CoA-DESS-R
	Bubble Pack	< 2.0	< 2.0	< 2.0	< 2.0	< 100.0	< 90.0	CoA-BUBP-R

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Document History Page

Document Title: 24L SOJ PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET
Document Number: 001-16413

Rev.	ECN No.	Orig. of Change	Description of Change
**	1166826	HLR	Initial spec release.
*A	2779779	MAHA	Added material declaration for assembly site 2.
*B	2826000	FRA	Minor change: Change CML with WEB in distribution list.
*C	3248241	HLR	Removed Assembly Site 1 – Omedata. (Site Closed)

Distribution: WEB

Posting: None

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